

ABSTRACT OF THE DISCLOSURE

A semiconductor device can perform resin sealing of an under-fill region and peripheral portion on the side of a semiconductor chip in the same process step, with shortening periods required for filling and curing the under-fill resin and avoiding formation of an internal void, and can simplify fabrication process and component parts. The semiconductor device includes a through opening provided at a predetermined position of the wired substrate, an under-fill region as a gap portion between the wired substrate and the semiconductor chip, and a molded resin portion as peripheral portion along side edge of the semiconductor chip. The molded resin portion and the through opening are sealed by resin, and a region where a distance between a connection surface with the semiconductor chip of the wired substrate and a resin surface of the molded resin portion is greater than a distance between the connection surface with the semiconductor chip of the wired electrode and a back surface of the semiconductor chip, being formed in the molded resin portion.